# **Specification of Thermoelectric Module**

TEHC1-12714

# **Description**

The 127 couples, 50 mm × 50 mm size single module which is made of our high performance ingot to achieve superior cooling performance and 74 °C or larger delta Tmax, is designed for superior cooling and heating applications. Beyond the standard below, we can design and manufacture the custom made module according to your special requirements.

#### Features

- High effective cooling and efficiency
- No moving parts, no noise, and solid-state
- Compact structure, small in size, light in weight
- Environmental friendly, RoHS compliant
- Precise temperature control
- Exceptionally reliable in quality, high performance

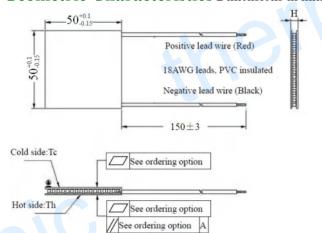
# **Application**

- Food and beverage service refrigerator
- Portable cooler box for cars
- Temperature stabilizer
- Liquid cooling
- CPU cooler and scientific instrument
- Photonic and medical systems

# **Performance Specification Sheet**

Th (°C)	27	50	Hot side temperature at environment: dry air, N <sub>2</sub>	
DT <sub>max</sub> (°C)	74	83	Temperature Difference between cold and hot side of the module when cooling capacity is zero at cold side	
U <sub>max</sub> (Voltage)	16.8	18.06	Voltage applied to the module at DT <sub>max</sub>	
I <sub>max</sub> (Amps)	14	14	DC current through the modules at DT <sub>max</sub>	
Q <sub>Cmax</sub> (Watts)	146	164	Cooling capacity at cold side of the module under DT=0 °C	
AC resistance (Ohms)	0.93	1.02	The module resistance is tested under AC	
Tolerance (%)	± 10		For thermal and electricity parameters	

# Geometric Characteristics Dimensions in millimeters



# **Ordering Option**

C CC	Thickness	Flatness/	Lead wire length (mm)		
Suffix	H / (mm)	Parallelism (mm)	Standard/Optional length		
TF	0:4.3±0.1	0:0.1/0.1	150±3/Specify		
TF	1:4.3±0.05	1:0.05/0.05	150±3/Specify		
Eg. TF00: Thickness 4.3±0.1(mm) and Flatness 0.05/0.05(mm)					

# **Manufacturing Options**

#### A. Solder:

1. T100: BiSn (Tmelt=138°C)

1. NS: No sealing (Standard)

2. T200: CuAgSn (Tmelt = 217°C)

2. SS: Silicone sealant

B. Sealant:

3. T240: SbSn (Tmelt =  $240^{\circ}$ C)

3. EPS: Epoxy sealant

#### C. Ceramics:

# **D. Ceramics Surface Options:**

AlO: Alumina (Al2O3, white 96%)

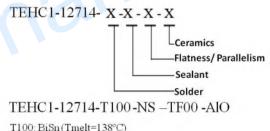
1. Alumina (Al<sub>2</sub>O<sub>3</sub>, white 96%)

1. Blank ceramics (not metalized)

2. Aluminum Nitride (AlN)

2. Metalized

# Naming for the Module

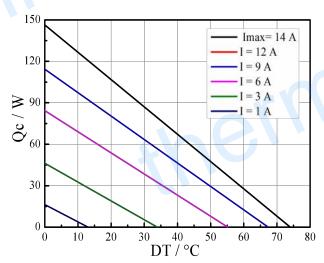


NS: No sealing

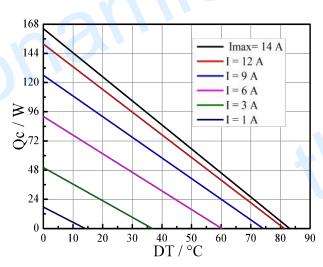
# **Specification of Thermoelectric Module**

# **TEHC1-12714**

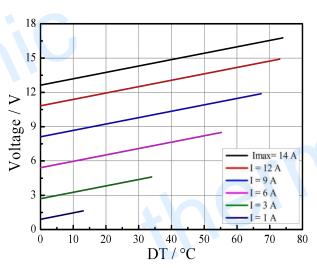
### Performance Curves at Th=27 °C

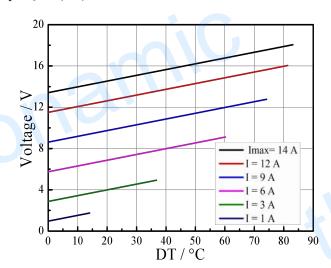


# Performance Curves at Th=50 °C

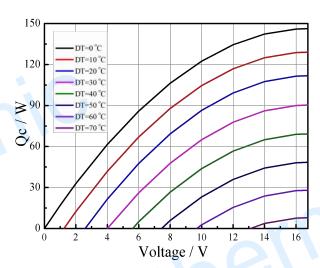


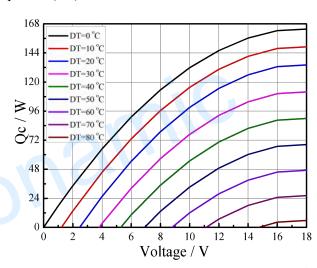
Standard Performance Graph Qc= f(DT)





Standard Performance Graph V = f(DT)



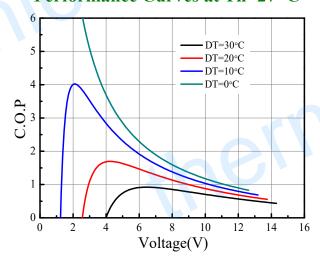


Standard Performance Graph Qc = f(V)

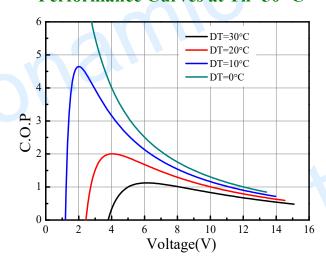
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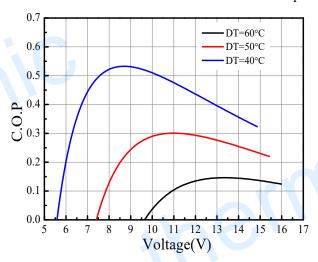
### Performance Curves at Th=27 °C

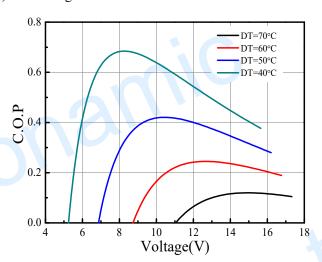


# Performance Curves at Th=50 °C



Standard Performance Graph COP = f(V) of DT ranged from 0 to 30 °C





Standard Performance Graph COP = f(V) of DT ranged from 40 to 60/70 °C

Remark: The coefficient of performance (COP) is the cooling power Qc/Input power (V × I).

# **Operation Cautions**

- Attach the cold side of module to the object to be cooled
- Attach the hot side of module to a heat radiator for heat dissipating
- Operation below I<sub>max</sub> or V<sub>max</sub>
- Work under DC